

General Description

The AO6808/L uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch. It is ESD protected.

AO6808 and AO6808L are electrically identical.

-RoHS Compliant

-AO6808L is Halogen Free

Features

$V_{DS} = 20V$

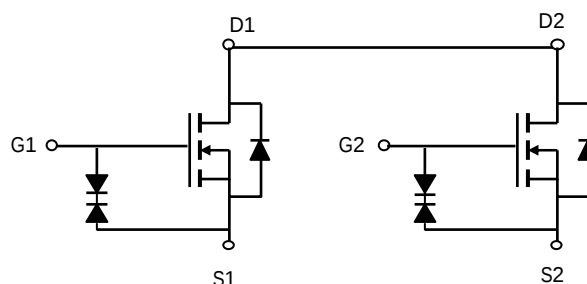
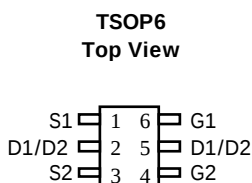
$I_D = 6A$ ($V_{GS} = 4.5V$)

$R_{DS(ON)} = 19m\Omega$ (typical) ($V_{GS} = 4.5V$)

$R_{DS(ON)} = 20m\Omega$ (typical) ($V_{GS} = 4.0V$)

$R_{DS(ON)} = 21m\Omega$ (typical) ($V_{GS} = 3.1V$)

$R_{DS(ON)} = 23m\Omega$ (typical) ($V_{GS} = 2.5V$)



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	10 Sec	Steady State	Units
Drain-Source Voltage	V_{DS}	20		V
Gate-Source Voltage	V_{GS}	± 12		V
Continuous Drain Current ^A	$T_A=25^\circ C$	6	4.6	A
	$T_A=70^\circ C$	4.6	3.7	
Pulsed Drain Current ^B	I_{DM}	60		
Power Dissipation ^A	$T_A=25^\circ C$	1.3	0.8	W
	$T_A=70^\circ C$	0.8	0.5	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10s$	$R_{\theta JA}$	76	95	$^\circ C/W$
Maximum Junction-to-Ambient ^A Steady State		118	150	$^\circ C/W$
Maximum Junction-to-Lead ^C Steady State	$R_{\theta JL}$	54	68	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20V, V _{GS} = 0V T _J = 55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} = 0V, V _{GS} = ±10V			±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250μA	0.5	0.75	1	V
I _{D(ON)}	On state drain current	V _{GS} = 4.5V, V _{DS} = 5V	60			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = 4.5V, I _D = 6.0A T _J =125°C	15 21	19 27	23 33	mΩ
		V _{GS} = 4.0V, I _D = 5.5A	15	20	25	mΩ
		V _{GS} = 3.1V, I _D = 5A	16	21	27	mΩ
		V _{GS} = 2.5V, I _D = 2A	17	23	30	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 5V, I _D = 6.0A		34		S
V _{SD}	Diode Forward Voltage	I _S = 1A,V _{GS} = 0V		0.65	1	V
I _S	Maximum Body-Diode Continuous Current				1.3	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, f=1MHz		620	780	pF
C _{oss}	Output Capacitance			125		pF
C _{rss}	Reverse Transfer Capacitance			64		pF
SWITCHING PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} = 10V, V _{DS} = 10V, I _D = 6A		16.2	21	nC
Q _g (4.5V)	Total Gate Charge			7.7	10	nC
Q _{gs}	Gate Source Charge			1.5		nC
Q _{gd}	Gate Drain Charge			2.7		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =10V, R _L =1.7Ω, R _{GEN} =3Ω		236		ns
t _r	Turn-On Rise Time			448		ns
t _{D(off)}	Turn-Off DelayTime			9.5		μs
t _f	Turn-Off Fall Time			4.1		μs
t _{rr}	Body Diode Reverse Recovery Time	I _F =6A, dI/dt=100A/μs		25	33	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =6A, dI/dt=100A/μs		9		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. In any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using $< 300\mu\text{s}$ pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

Rev0 April 2008

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

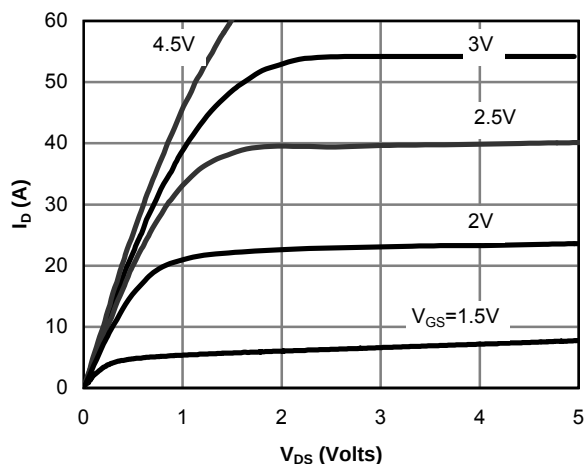


Figure 1: On-Region Characteristics

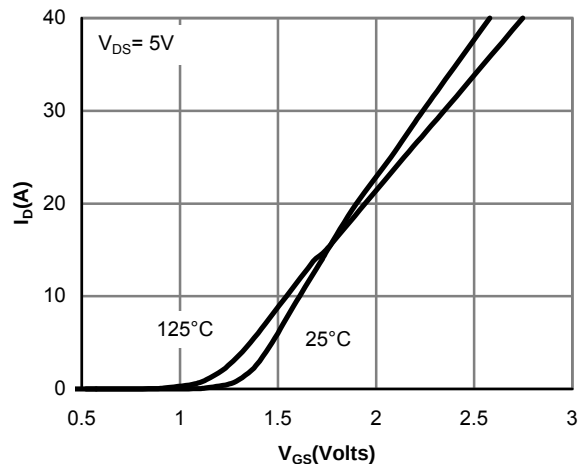


Figure 2: Transfer Characteristics

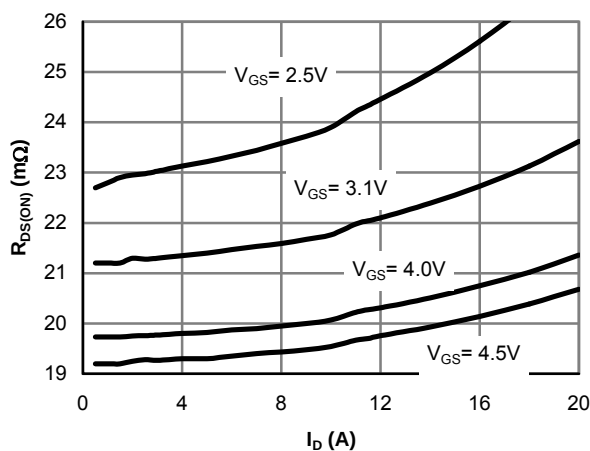


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

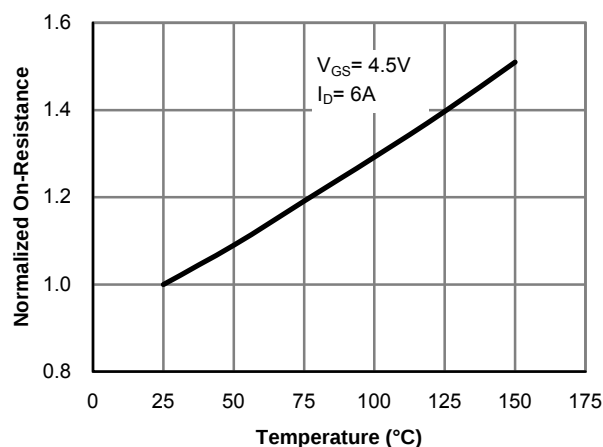


Figure 4: On-Resistance vs. Junction Temperature

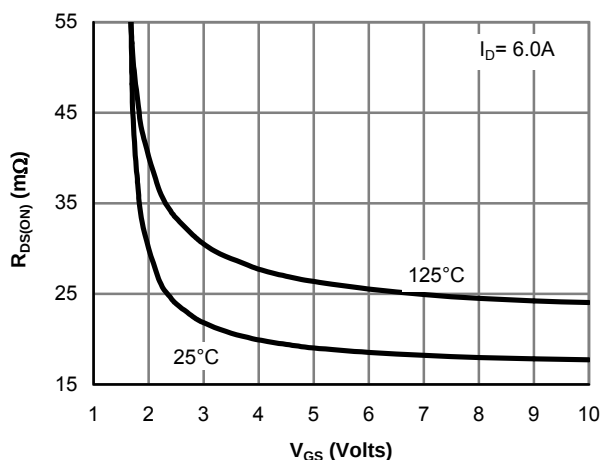


Figure 5: On-Resistance vs. Gate-Source Voltage

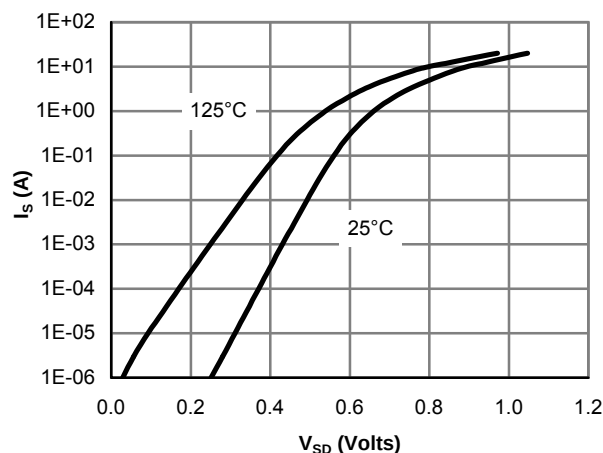


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

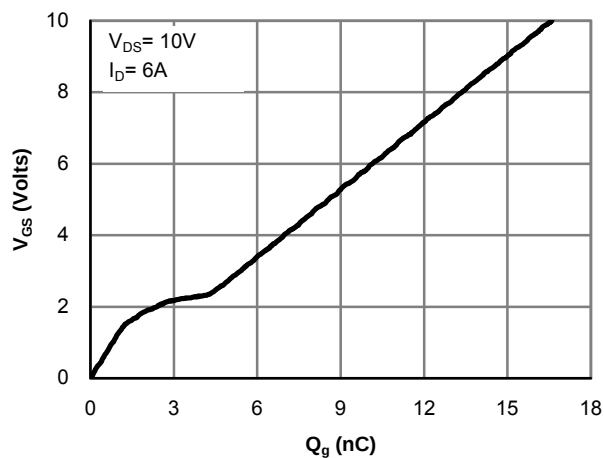


Figure 7: Gate-Charge Characteristics

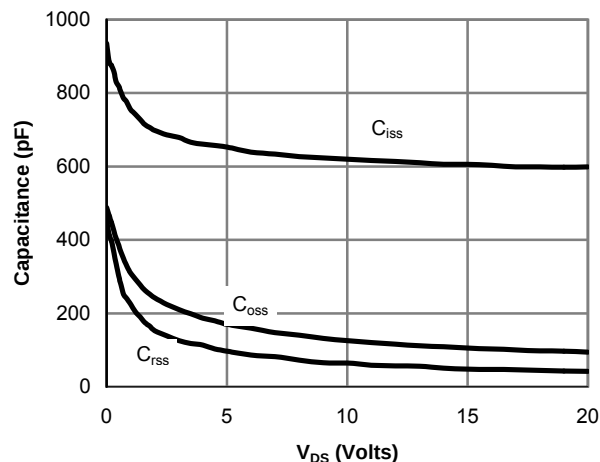


Figure 8: Capacitance Characteristics

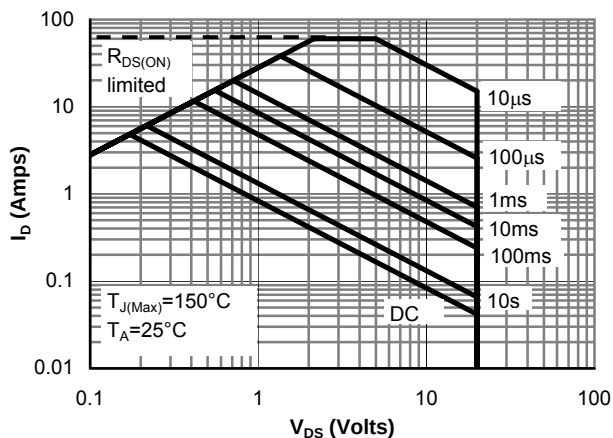


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

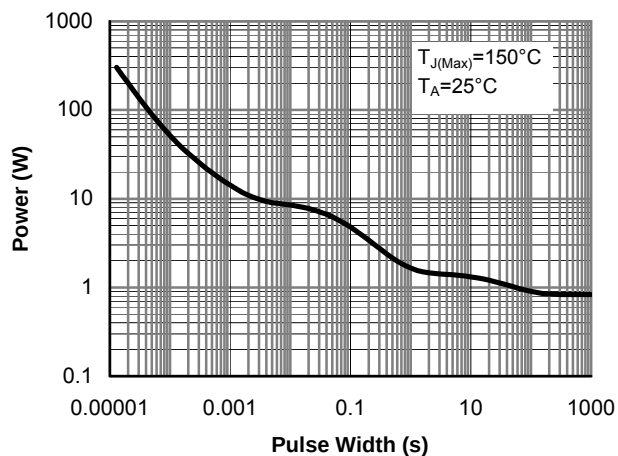


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

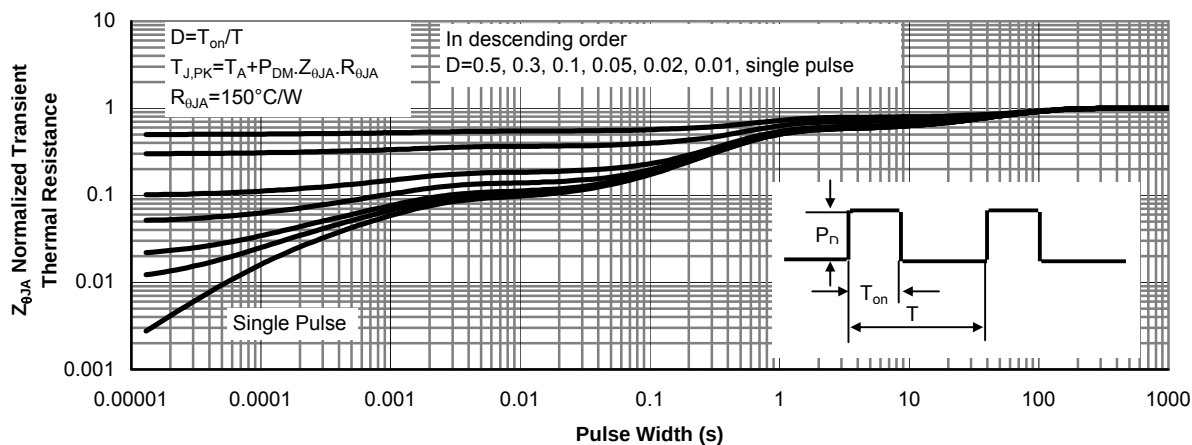


Figure 11: Normalized Maximum Transient Thermal Impedance (Note E)